

Listing of Claims

1 - 10. (canceled)

11. (previously presented) A prepreg obtained by impregnating a cyanate-epoxy resin comprising

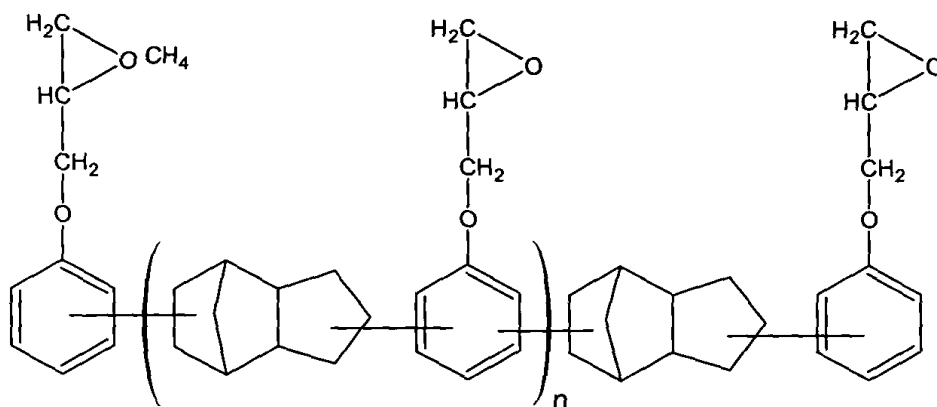
(A) a prepolymer of a cyanate compound containing two or more cyanato groups in one molecule thereof with a conversion of the monomer of 10 to 70 mole %, in an amount of 100 parts by weight,

(B) an epoxy resin in an amount of 50 to 250 parts by weight,

(C) a curing accelerator in an amount of 0.1 to 5 parts by weight, and

(D) an antioxidant in an amount of 0.1 to 20 parts by weight, as main components,

wherein the epoxy resin (B) is derived from a dicyclopentadiene-phenol polyaddition product having a dicyclopentadiene skeleton represented by the following formula (1):



(1)

wherein n is 0 or a positive integer, and the curing accelerator comprises (i) a compound (C) having a catalytic function to accelerate the curing reaction of said cyanate compound (A) and (ii) a compound having a catalytic function to accelerate the curing reaction of said epoxy resin (B),

in a base, and drying the same.

12. (previously presented) A prepreg according to claim 11, wherein the compound having a catalytic function to accelerate the curing reaction of said cyanate compound (A) is an organic metal salt or an organic metal complex, and the compound having a catalytic function to accelerate the curing reaction of the epoxy resin (B) is an imidazole compound.

13. (previously presented) A prepreg according to claim 12, wherein the organic metal salt or the organic metal complex is an organic metal salt or an organic metal complex of iron, copper, zinc, cobalt, nickel, manganese or tin.

14. (previously presented) A metal foil-laminated plate obtained by laminating a metal foil on one side or both sides of the prepreg of Claim 11 or a laminate thereof, and subjecting the laminate to hot-press molding.

15. (previously presented) A printed wiring board obtained by conducting a circuit-forming work on the metal foil of the metal foil-laminated plate of Claim 14.

16. (previously presented) A prepreg according to Claim 11, wherein the compound having a catalytic function to accelerate the curing reaction of the cyanate compound (A) is at least one of the organic metal salts or organic metal complexes of one or more of the metals selected from the group consisting of iron, copper, zinc, cobalt, nickel, manganese and tin, and the compound having a catalytic function to accelerate the curing reaction of the epoxy resin (B) is at least one compound selected from the group consisting of imidazole and its derivatives, organic phosphorus compounds, secondary amines, tertiary amines and quaternary ammonium salts.

17. (new) A prepreg according to claim 11, wherein the antioxidant is at least one member selected from the group consisting of phenolic antioxidants and organic sulfur compound antioxidants.

18. (new) A prepreg according to claim 17, wherein the phenolic antioxidant is at least one member selected from the group consisting of pyrogallol, butylated hydroxyanisole, 2, 6-di-t-butyl-4-methylphenol, 2,2' -methylene-bis- (4-methyl-6-t-butylphenol), 4,4' -thiobis- (3-methyl-6-t-butyl-phenol), 1,3,5-trimethyl-2,4,6-tris (3,5-di-t-butyl-4-hydroxybenzyl)benzene, and tetrakis-[methylene-3-(3' -5' -di-t-butyl-4' -hydroxyphenyl) propionate] methane.

19. (new) A prepreg according to claim 17, wherein the organic sulfur compound antioxidant is at least one member selected from the group consisting of dilauryl thiodipropionate and distearyl thiodipropionate.